

# 24 / D

- 1 -

Docket No. 0756-1914 11-15-02  
Muller

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of )

Art Unit: 2813

Shunpei YAMAZAKI et al. )

Examiner: L. Schillinger

Serial No. 09/235,770 )

Filed: January 25, 1999 )

For: SEMICONDUCTOR DEVICE )

AND METHOD FOR FORMING )

THE SAME )

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with  
The United States Postal Service with sufficient postage as First  
Class Mail in an envelope addressed to: Commissioner for Patents,  
Washington, D.C. 20231, on 11/14/02

AMENDMENT

Honorable Commissioner of Patents

Washington, D.C. 20231

Sir:

In response to the Office Action dated June 4, 2002 please amend the above-  
identified application as follows:

IN THE CLAIMS:

Please amend claims 3, 6, 9, 13, 16 and 19 as follows:

RECEIVED  
NOV 13 2002  
TECHNOLOGY CENTER 2800

D<sup>1</sup> 3. (Amended) A semiconductor device according to claim 1 wherein a  
thickness of said first insulating film is 10-50 nm, a thickness of said second insulating  
film is 100-800 nm, a thickness of said third insulating film is 50-200 nm and a thickness  
of said fourth insulating film is 2-20 nm.

D<sup>2</sup> 6. (Amended) A semiconductor device according to claim 4 wherein a  
thickness of said first insulating film is 10-50 nm, a thickness of said second insulating  
film is 100-800 nm, a thickness of said third insulating film is 50-200 nm and a thickness  
of said fourth insulating film is 2-20 nm.

46

D